



## Silicon Carbide Dual Schottky Power Rectifier 5A, 1200V

### DESCRIPTION

These dual 1200 V rated SiC Schottky rectifiers are in a hermetically sealed package with options for common cathode, common anode, and doubler configurations. They offer very fast switching capabilities with greater efficiency at higher operating temperatures compared to existing ultrafast silicon rectifiers.

**Important:** For the latest information, visit our website <http://www.microsemi.com>.

### FEATURES

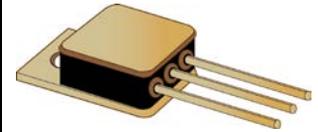
- TO-257 package.
- Lightweight.
- Hermetically sealed package.
- Internal metallurgical bonds.
- High temperature ( $T_J$ ) +175 °C.
- Zero reverse recovery current.
- Temperature independent switching behavior.
- Very fast switching compared to fast or ultrafast rectifiers.
- Positive  $V_F$  temperature coefficient (parallel devices for higher currents).
- RoHS compliant versions are available.

### APPLICATIONS / BENEFITS

- Schottky barrier diode for military, space and other high reliability applications.
- Switching power supplies or other applications requiring extremely fast switching and essentially no switching losses.
- High forward surge capability.
- High reverse voltage capability with very fast switching.
- Inherently radiation hard >100 krads as described in Microsemi [MicroNote 050](#).

### MAXIMUM RATINGS @ $T_C = +25\text{ °C}$ unless otherwise noted.

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	$T_J$ and $T_{STG}$	-65 to +175	°C
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.6	°C/W
Working Peak Reverse Voltage	$V_{RWM}$	1200	V
Non-Repetitive Peak Inverse Voltage	$V_{RSM}$	1200	V
DC Blocking Voltage	$V_{DC}$	1200	V
Average DC Output Current @ 25 °C	$I_O$	5	A
Non-Repetitive Sinusoidal Surge Current @ $t_p = 8.3\text{ ms}$ , half sinewave, $I_O = 0$ ; $V_{RM} = 0$	$I_{FSM}$	30	A



**TO-257 Package**

Also available in:

**Dual U3 package**  
(surface mount)  
 [MSiCSS05120CC](#)

**TO-257 package**  
(lead)  
 [MSiCSN05120](#)

**TO-257 tabless package**  
(lead)  
 [MSiCSX05120](#)

**U4 package**  
(surface mount)  
 [MSiCSS05120](#)

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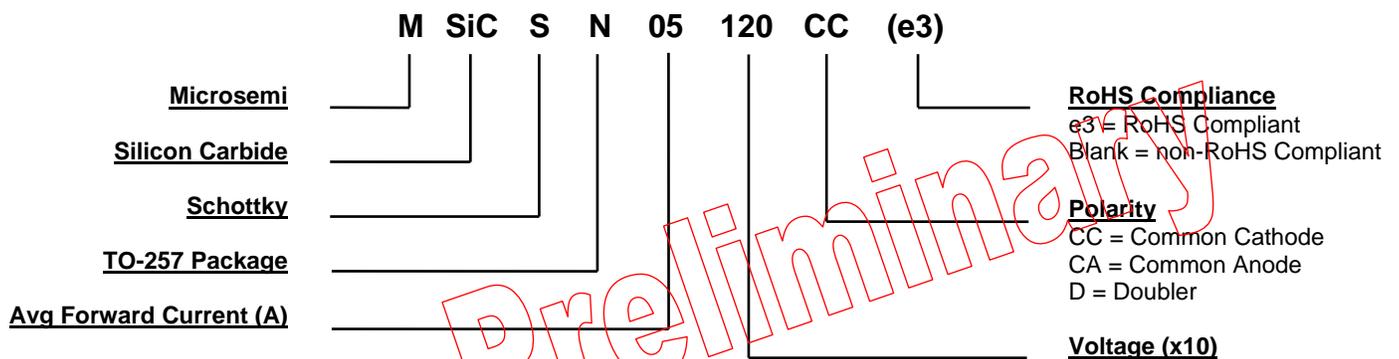
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**MECHANICAL and PACKAGING**

- CASE: Nickel plated copper base & 1020 steel frame.
- TERMINALS: Solder dipped copper cored 52 alloy or RoHS compliant matte/tin plating.
- MARKING: Alpha numeric.
- POLARITY: See [schematic](#) on last page.
- WEIGHT: Approximately 3.43 grams.
- See [Package Dimensions](#) on last page.

**PART NOMENCLATURE**

**SYMBOLS & DEFINITIONS**

Symbol	Definition
$C_J$	Junction Capacitance: The junction capacitance in pF at a specified frequency (typically 1 MHz) and specified voltage.
$I_F$	Forward Current: The forward current dc value, no alternating component.
$I_R$	Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
$T_J$	Junction Temperature: The temperature of a semiconductor junction.
$V_F$	Forward Voltage: The forward voltage the device will exhibit at a specified current (typically shown as maximum value).
$V_R$	Reverse Voltage: The reverse voltage dc value, no alternating component.

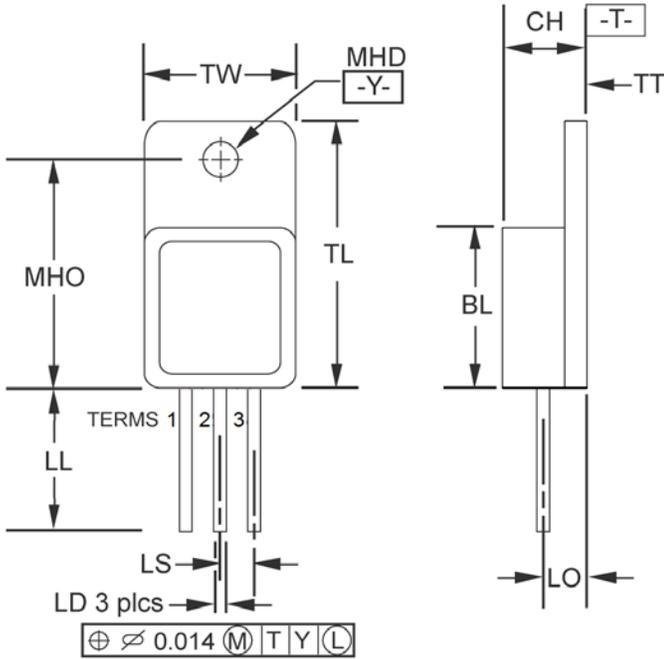
**ELECTRICAL CHARACTERISTICS @  $T_A = +25\text{ }^\circ\text{C}$  unless otherwise noted**

Parameters / Test Conditions	Symbol	Min.	Max.	Typ.	Unit
Forward Voltage* $I_F = 1\text{ A}, T_J = 25\text{ }^\circ\text{C}$ $I_F = 2.5\text{ A}, T_J = 25\text{ }^\circ\text{C}$ $I_F = 5.0\text{ A}, T_J = 25\text{ }^\circ\text{C}$	$V_F$		1.2 1.6 1.8		V
Reverse Current $V_R = 1200\text{ V}, T_J = 25\text{ }^\circ\text{C}$ $V_R = 1200\text{ V}, T_J = 175\text{ }^\circ\text{C}$	$I_R$		50 100		$\mu\text{A}$
Junction Capacitance $V_R = 0\text{ V}$ $f = 1\text{ MHz}$	$C_J$			500	pF

\* Pulse test: Pulse width 300  $\mu\text{sec}$ , duty cycle 2%.

Preliminary

PACKAGE DIMENSIONS



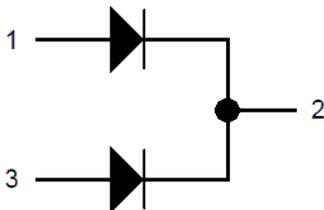
Ltr	Dimensions			
	Inch		Millimeters	
	Min	Max	Min	Max
BL	0.410	0.430	10.41	10.92
CH	0.190	0.200	4.83	5.08
LD	0.025	0.035	0.64	0.89
LL	0.505	0.595	12.82	15.11
LO	0.120 BSC		3.05 BSC	
LS	0.100 BSC		2.54 BSC	
MHD	0.140	0.150	3.56	3.81
MHO	0.527	0.537	13.39	13.64
TL	0.645	0.665	16.38	16.89
TT	0.035	0.045	0.89	1.14
TW	0.410	0.420	10.41	10.67
TERM 1	SEE SCHEMATIC			
TERM 2	OPEN (No connection)			
TERM 3	SEE SCHEMATIC			

NOTES:

1. Dimensions are in inches.
2. Millimeter equivalents are given for general information only.
3. Glass meniscus included in dimension TL and BL.

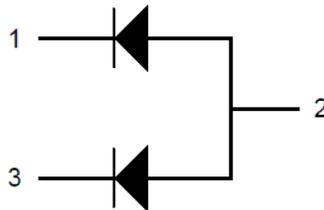
SCHEMATIC

CC - COMMON CATHODE



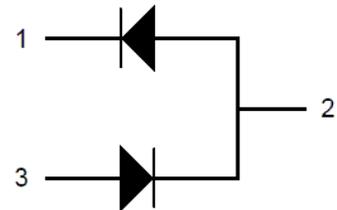
TERM 1 = ANODE  
 TERM 2 = CATHODE  
 TERM 3 = ANODE

CA - COMMON ANODE



TERM 1 = CATHODE  
 TERM 2 = ANODE  
 TERM 3 = CATHODE

D - DOUBLER



TERM 1 = CATHODE  
 TERM 2 = CENTER TAP  
 TERM 3 = ANODE